

PCGe Detector Fabrication in China

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Tsinghua University/CDEX collaboration

2015 Symposium of the Sino-German GDT Cooperation
@ Ringberg castle, Oct. 18-24, 2015



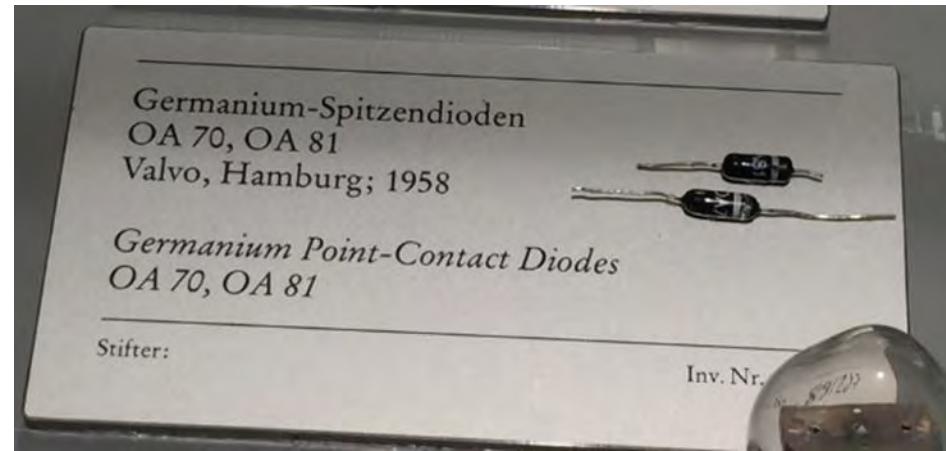
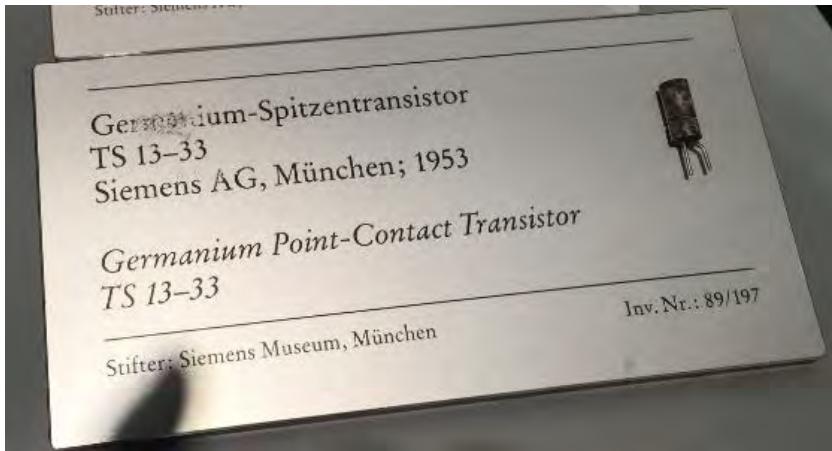
中国锦屏地下实验室
China Jinping Underground Laboratory

Outline

- Recent progress in detector fabrication
- The design of CDEX-10X detector module
- Summary & outlook

Ge and Point-Contact

Pictures taken at Deutsches Museum on Oct. 18th, 2015

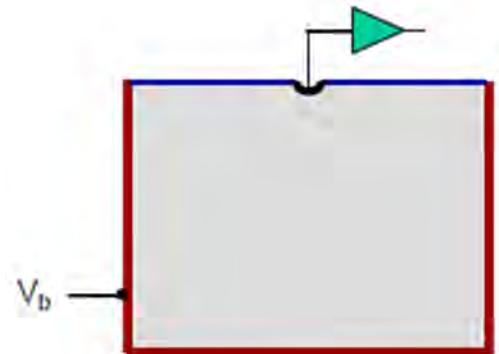


Ge Point-Contact Transistor

Ge Point-Contact Diodes

PCGe detector

- Late 1980s
- Large volume
- Low noise



Facilities @ THU for PCGe Detector

- Clean room



- Chemical Lab



- Mechanical workshop



- Test corner



Crystals Processed



New members recently:

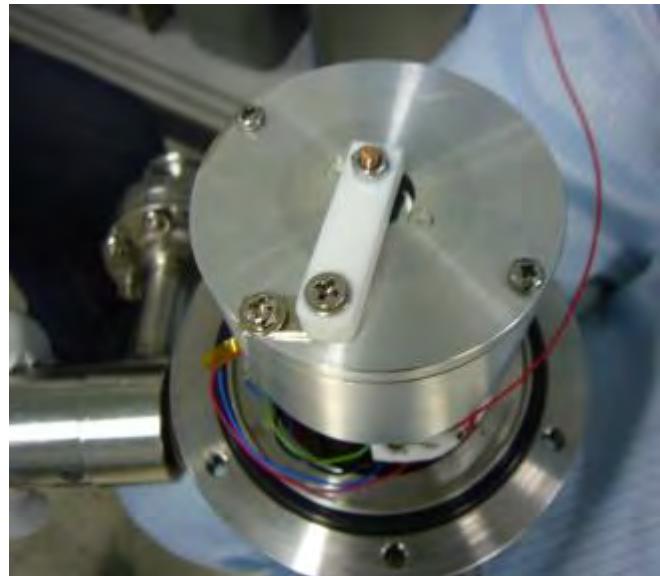
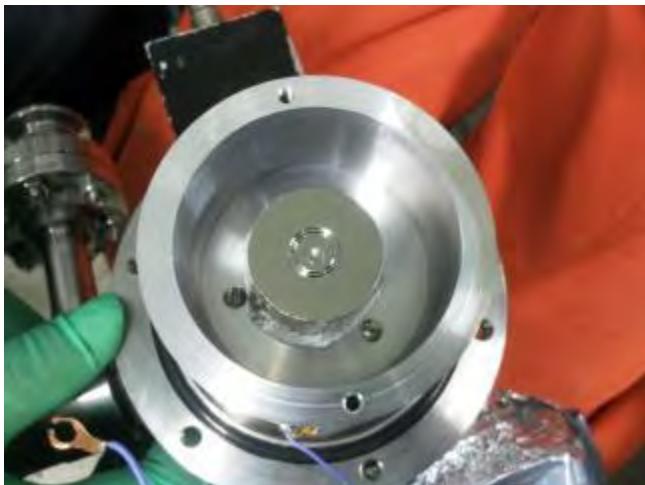
- PCGes:
 - 15#, 16#: $\phi 25\text{mm} \times 25\text{mm}$ (~65g)
 - 18#, 19#: $\phi 50\text{mm} \times 50\text{mm}$ (~500g)
 - Good performance
 - Will be used in CDEX-10X
- BEGe:
 - 21#: $\phi 50\text{mm} \times 30\text{mm}$

New surface treatment method and electrode configuration developed:

- Good performance: low leakage current, good long-term stability
- Easy to handle and assemble

Progress in PCGe detector fabrication(1)

- PCGe Detector-11# ($\varnothing 25\text{mm}$)
 - New surface treatment method
 - Chemical etching

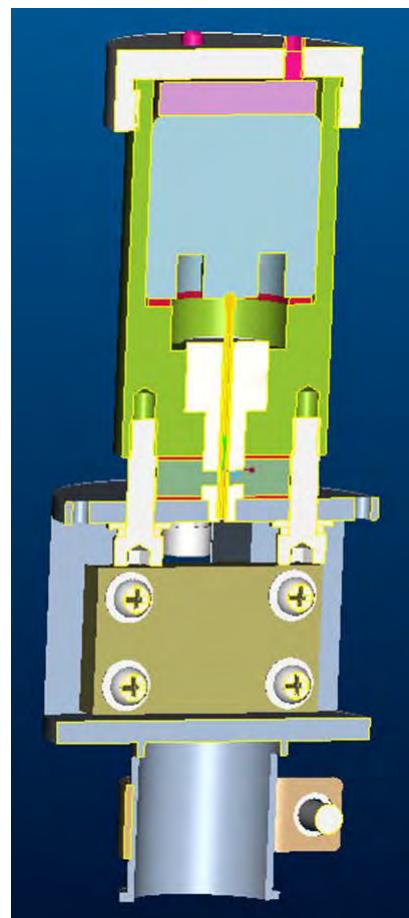


	Leakage Current										Energy Resolution(%)	
Before	Bias(V)	100	200	300	400	500	600	700	800		@Cs-137	@Am-241
	I_L (pA)	30	29	104	266	479	1277	6391	22313		0.273	1.69
After	Bias(V)	100	200	300	400	450	500	510	520	530	@Cs-137	@Am-241
	I_L (pA)	6	7	8	10	10	10	11	766	5591	0.198	1.08

Progress in PCGe detector fabrication

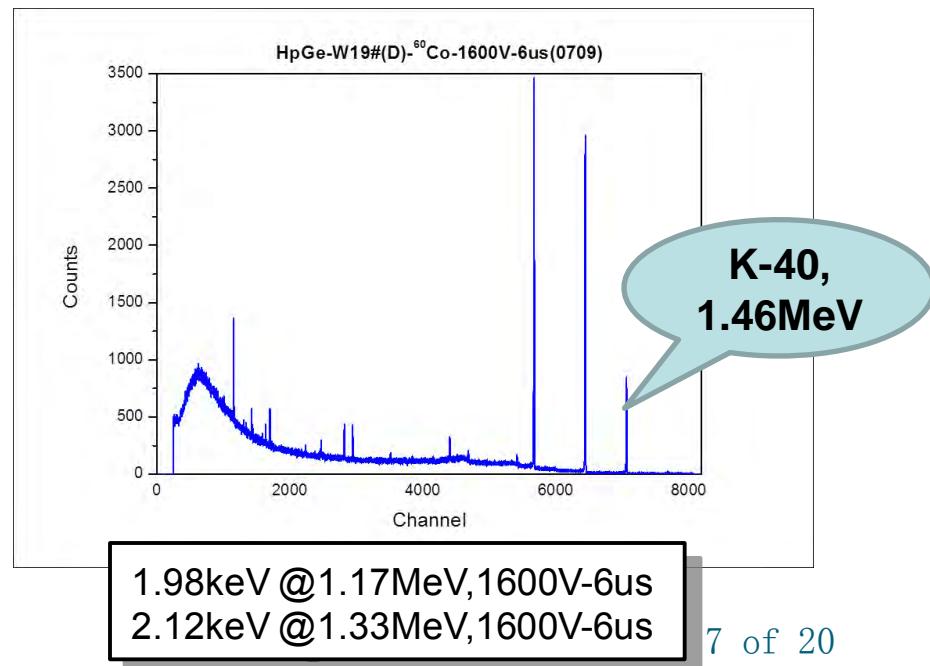
- PCGe Detector-19# ($\varnothing 50\text{mm}$)

- New surface treatment method
- New electrode configuration

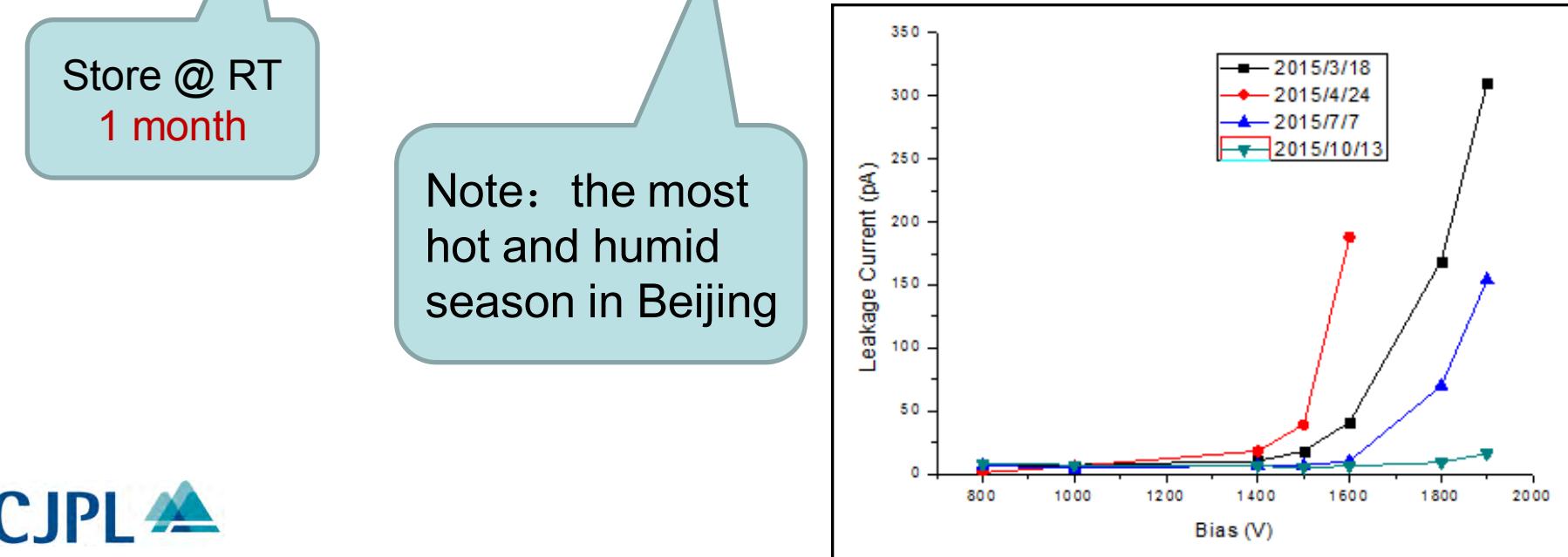
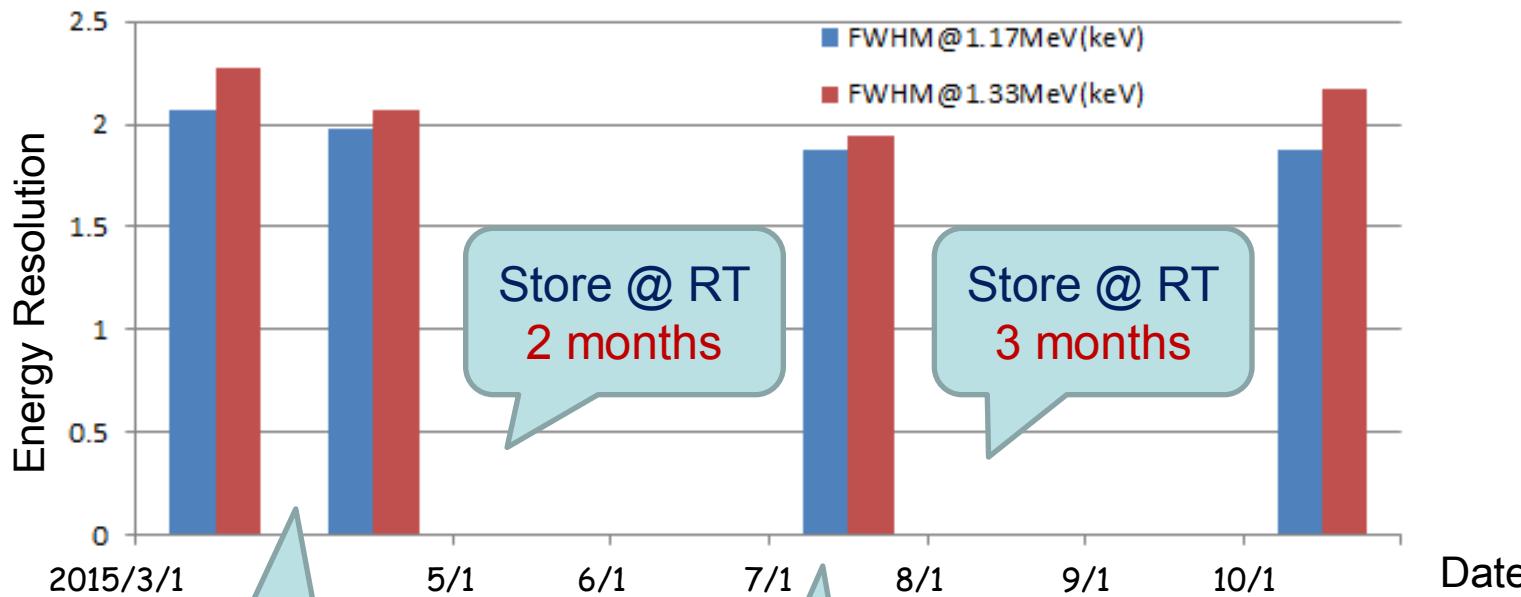


- Very good performance:

Bias (V)	800	900	1000	1100	1200
Leakage Current (pA)	1	3	6	7	13
Bias (V)	1300	1400	1500	1600	1700
Leakage Current (pA)	19	39	97	188	922



19# Detector: Thermal Cycle Test



21#, 1th BEGe detector

- Crystal size: $\phi 50 \text{ mm} \times 30\text{mm}$

• Am-241:

• 0.85KeV@59KeV,2000V-6us

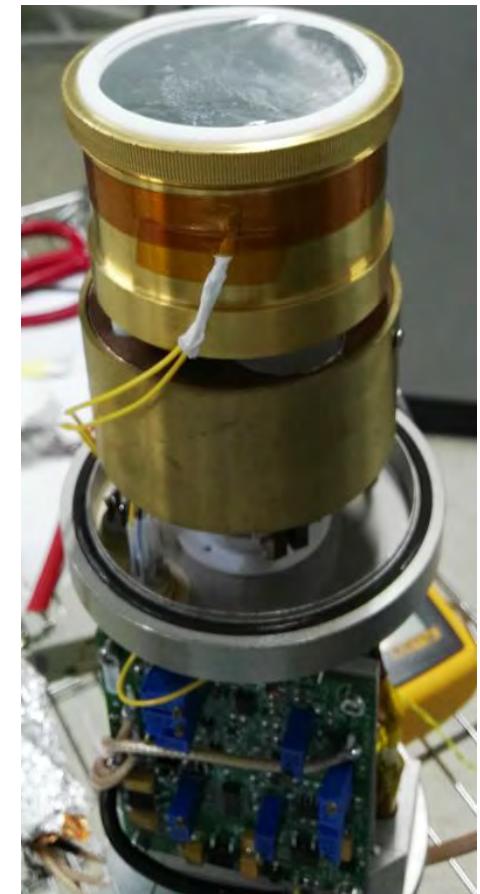
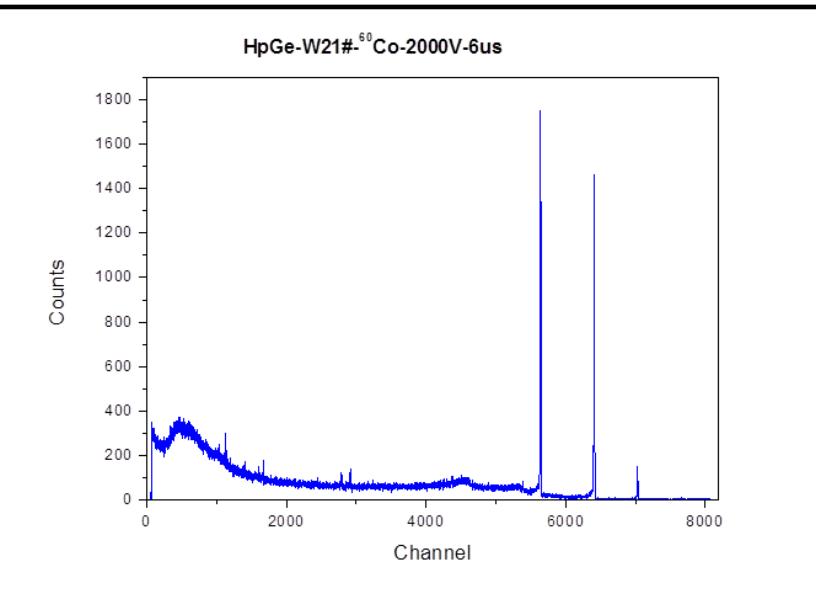
• Cs-137:

• 1.41KeV@662KeV,2000V-6us

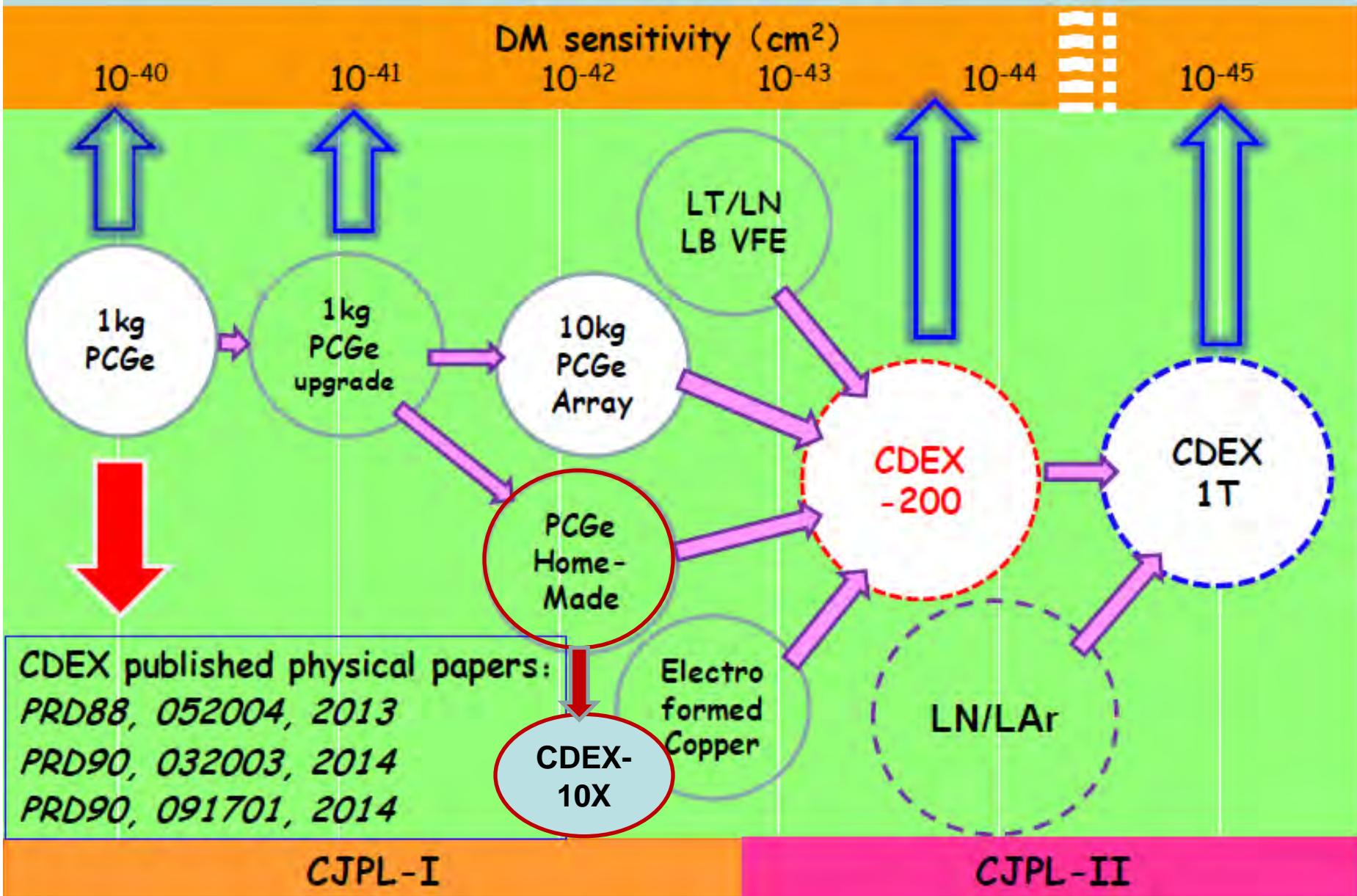
• Co-60:

• 1.89KeV@1.17MeV,2000V-6us

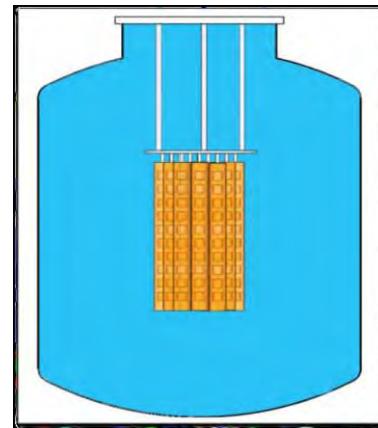
• 1.9KeV@1.33MeV,2000V-6us



CDEX's plan

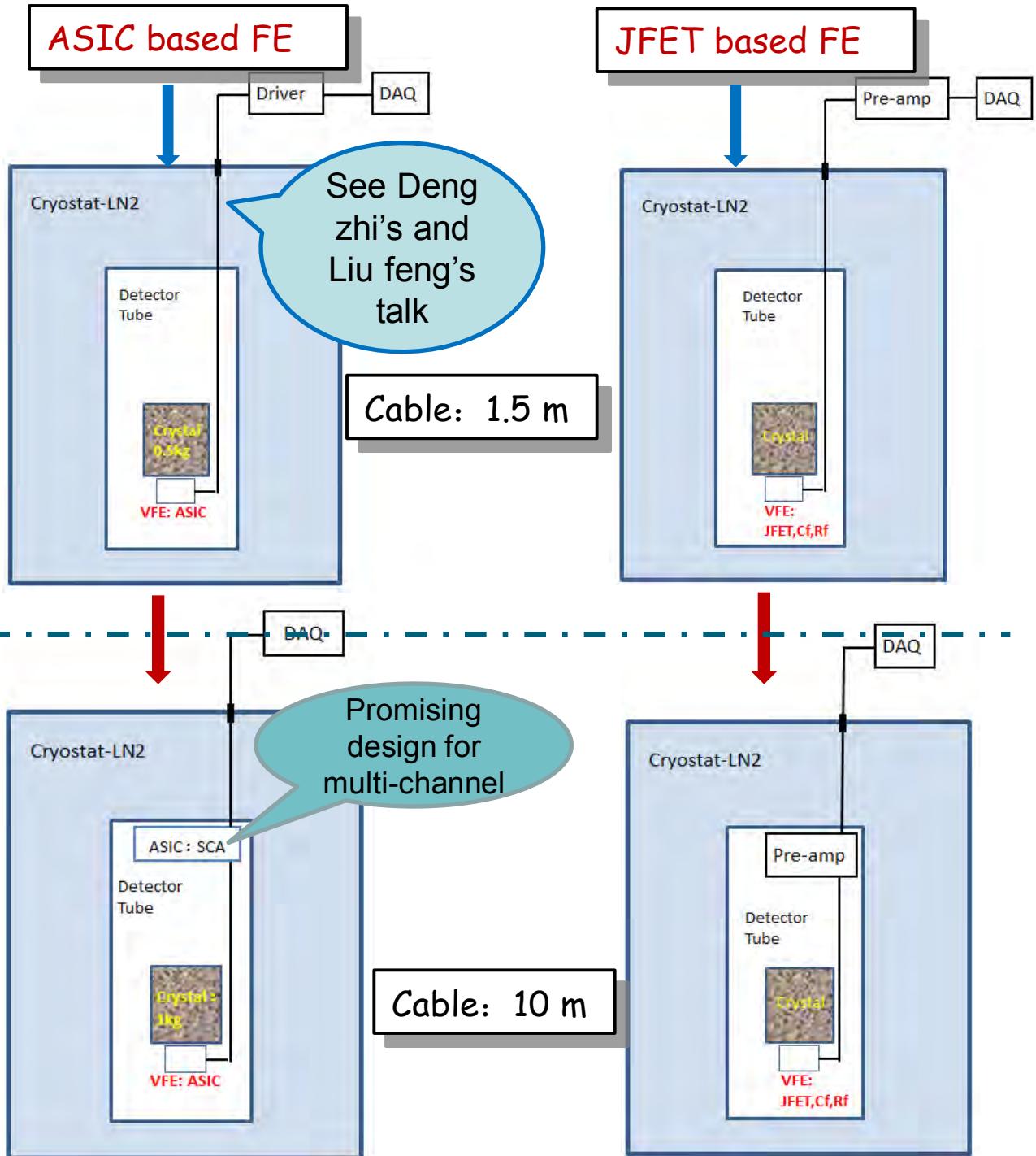
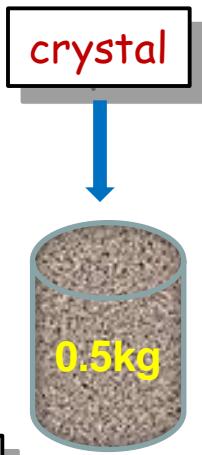


CDEX-10X



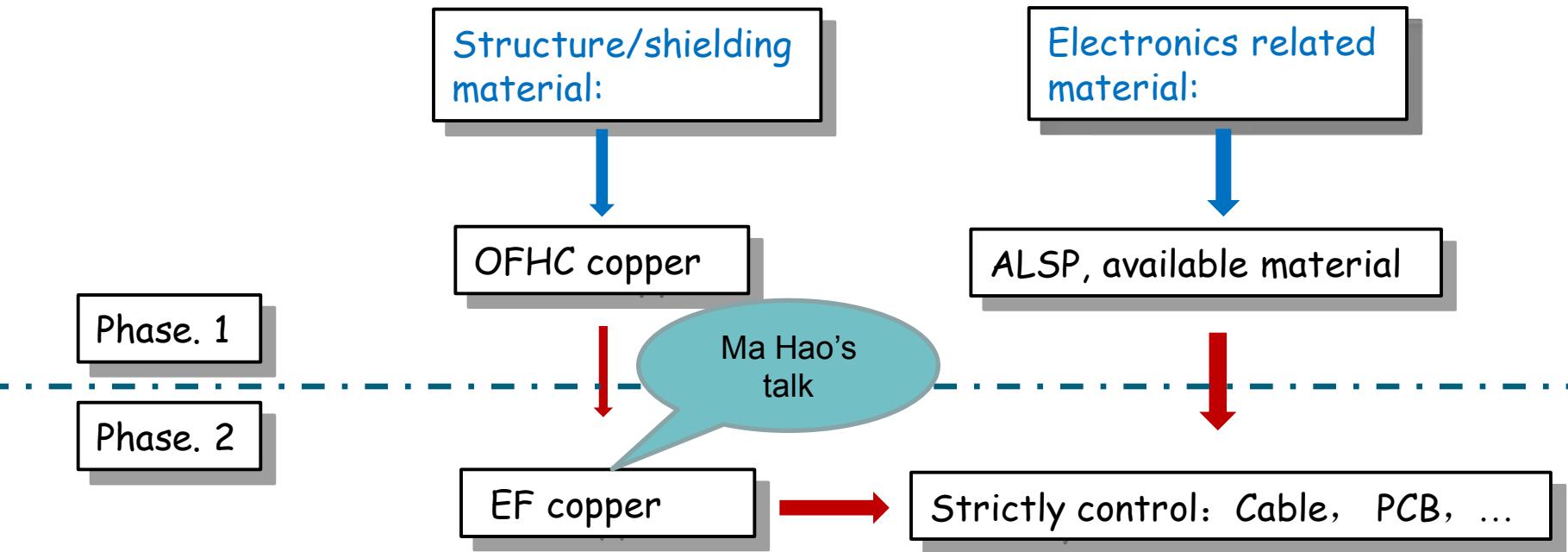
- Motivation:
 - pre-R&D for CDEX-200
 - Try to understand the key technology, especially low background
- Features:
 - PCGe detector
 - Crystals (string) sealed in a vacuum tube , then dip into LN2
- Challenges: mass & low threshold
 - Detector: **X=its mass**
 - Front-end electronics
 - JFET based
 - ASIC
 - Structure, low radioactive background material
 - ...

CDEX-10X design: Roadmap (1)



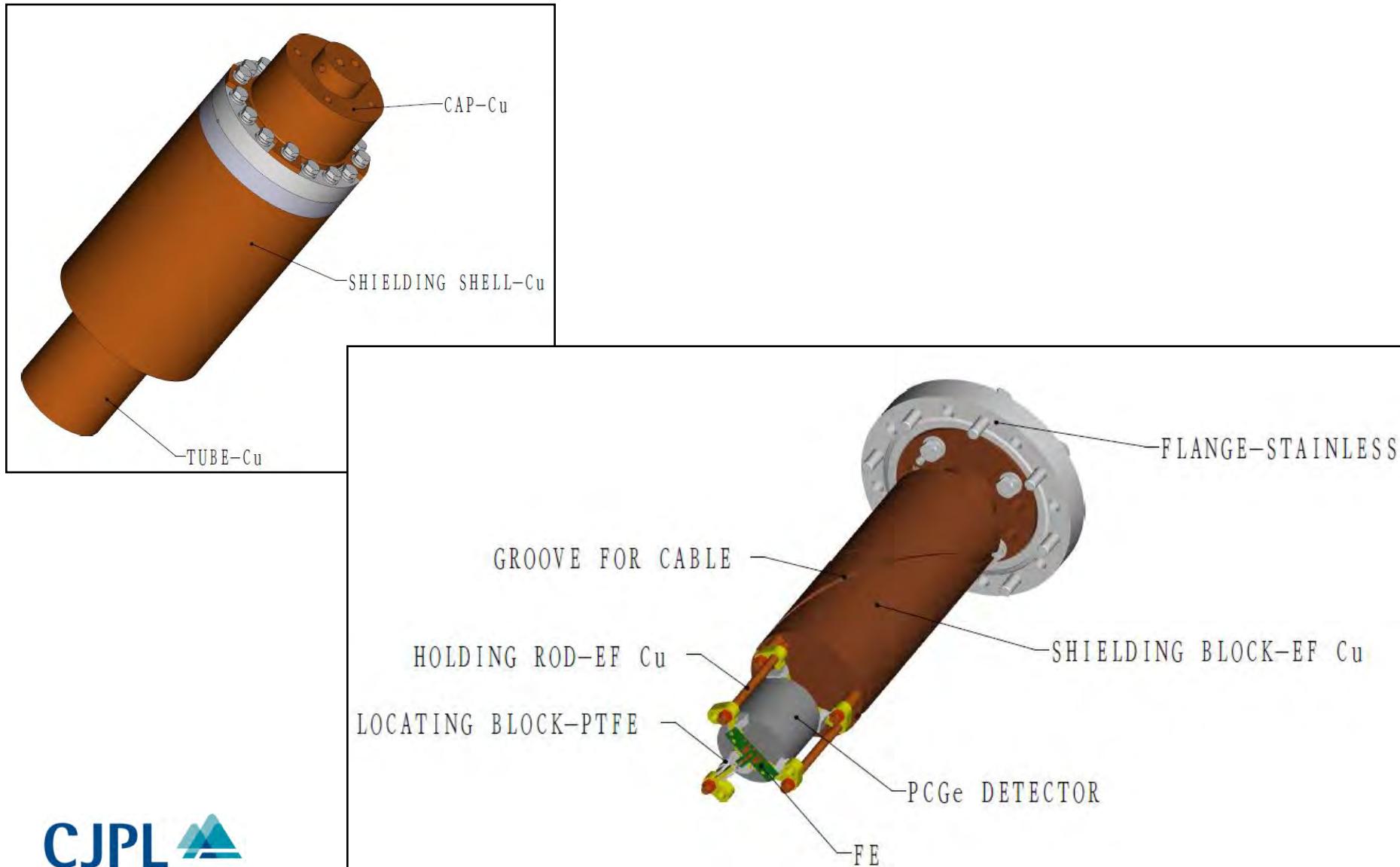
CDEX-10X design: Roadmap (2)

Low Background Control:

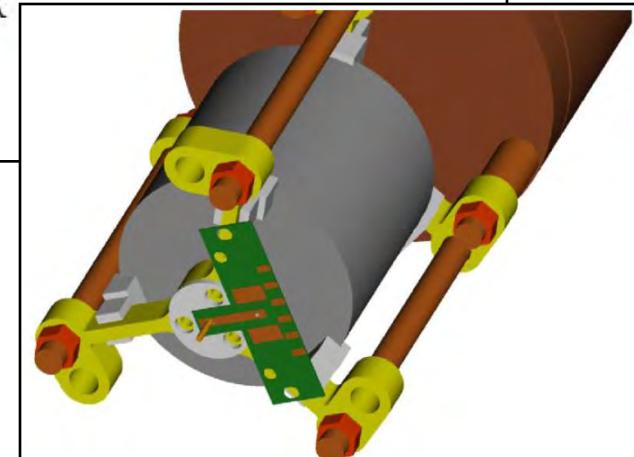
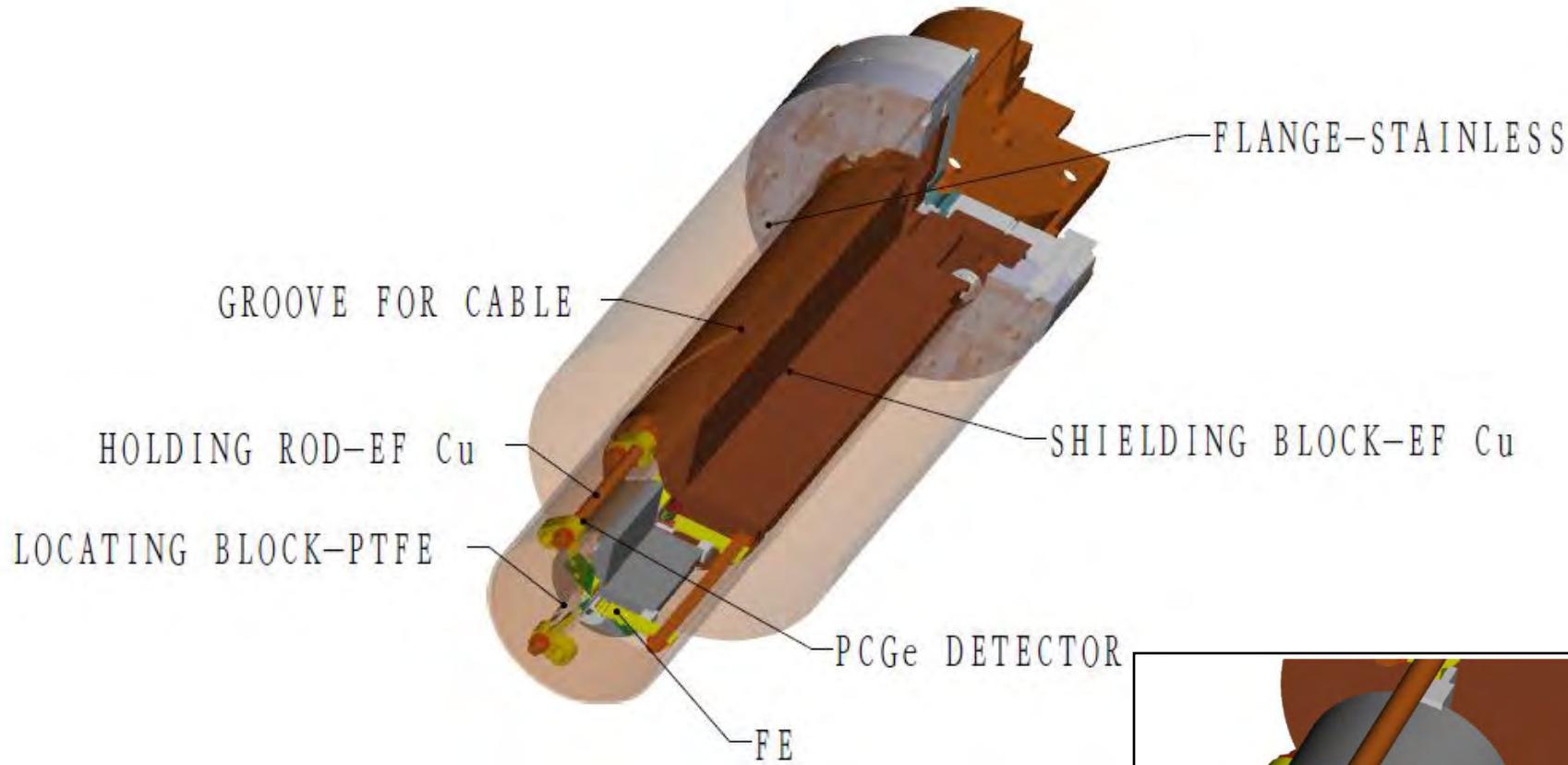


- ◆ Phase1: focus on functional test
- ◆ Phase2: focus on performance:
 - ◆ Simulation study and material screening is essential

CDEX-10X design: mechanical (1)

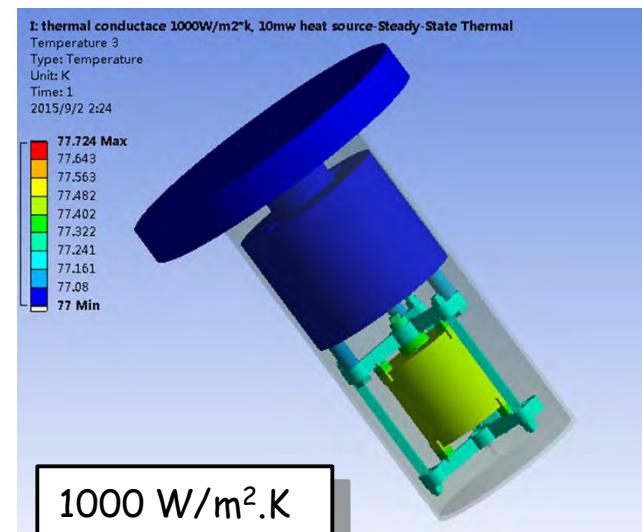
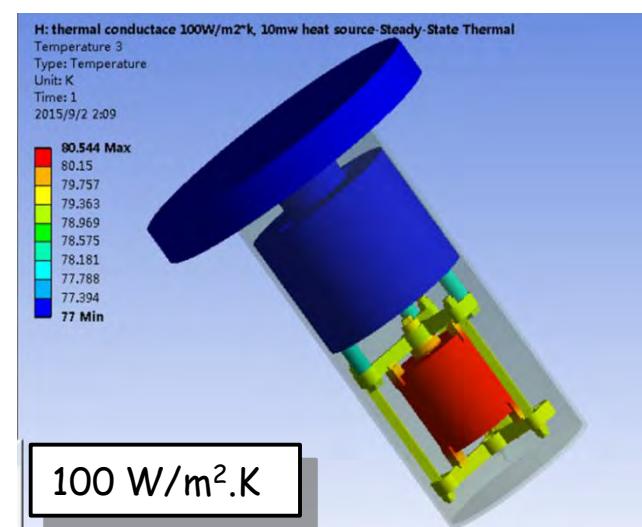
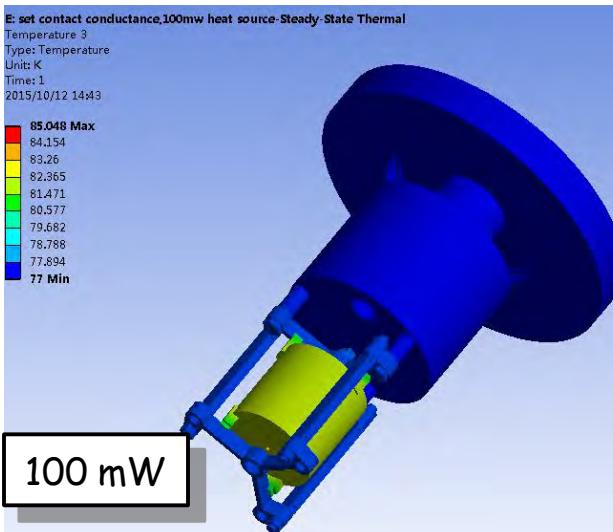
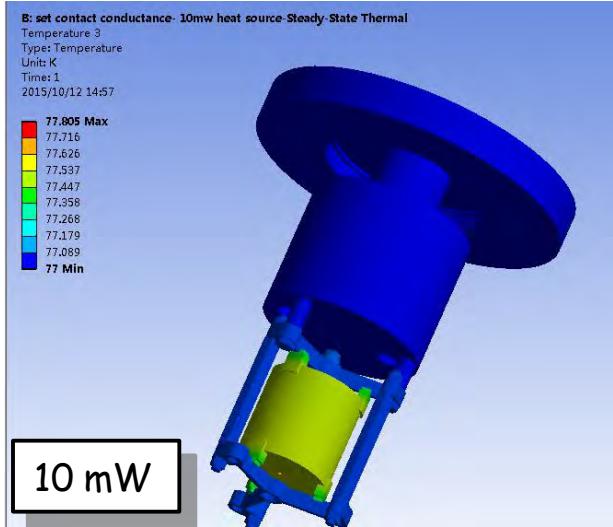


CDEX-10X design: mechanical (2)



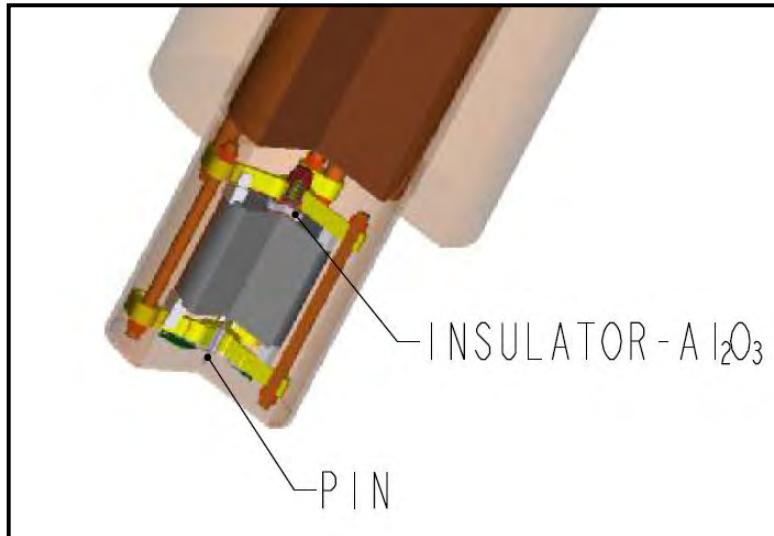
CDEX-10X design: Thermal Simulation Analysis (1)

- Different heat source:
- Different thermal conductance



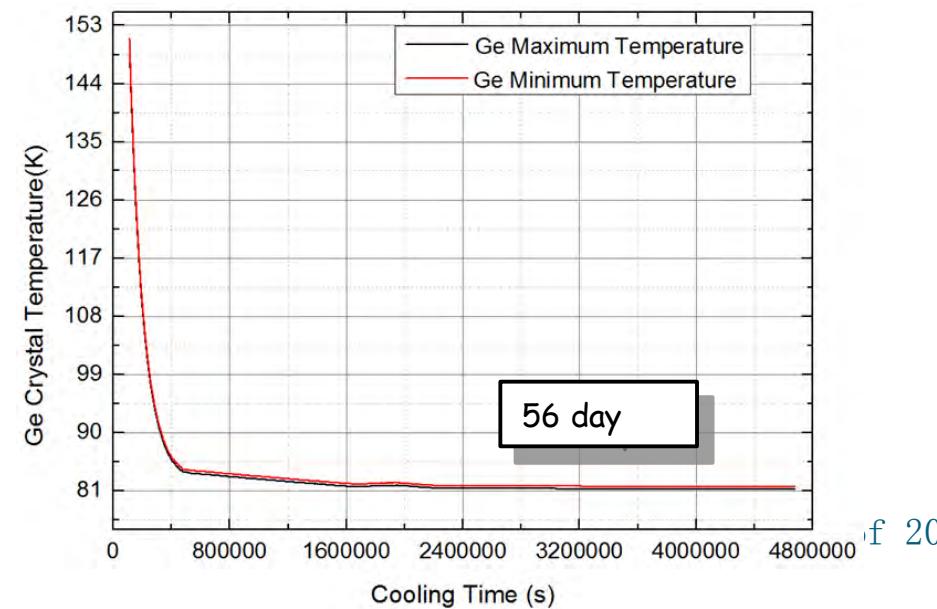
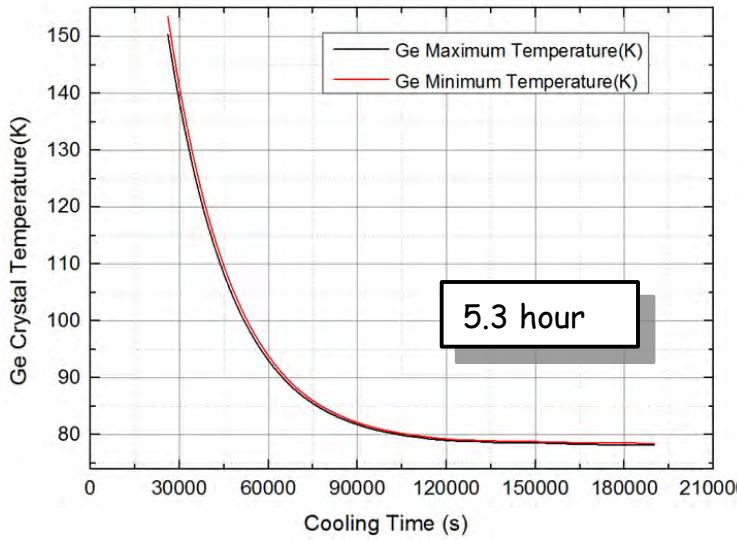
CDEX-10X design: Thermal Simulation Analysis (2)

- w/o Al_2O_3 :



W, 77.5K

w/o, 79.5K

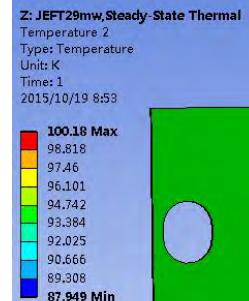
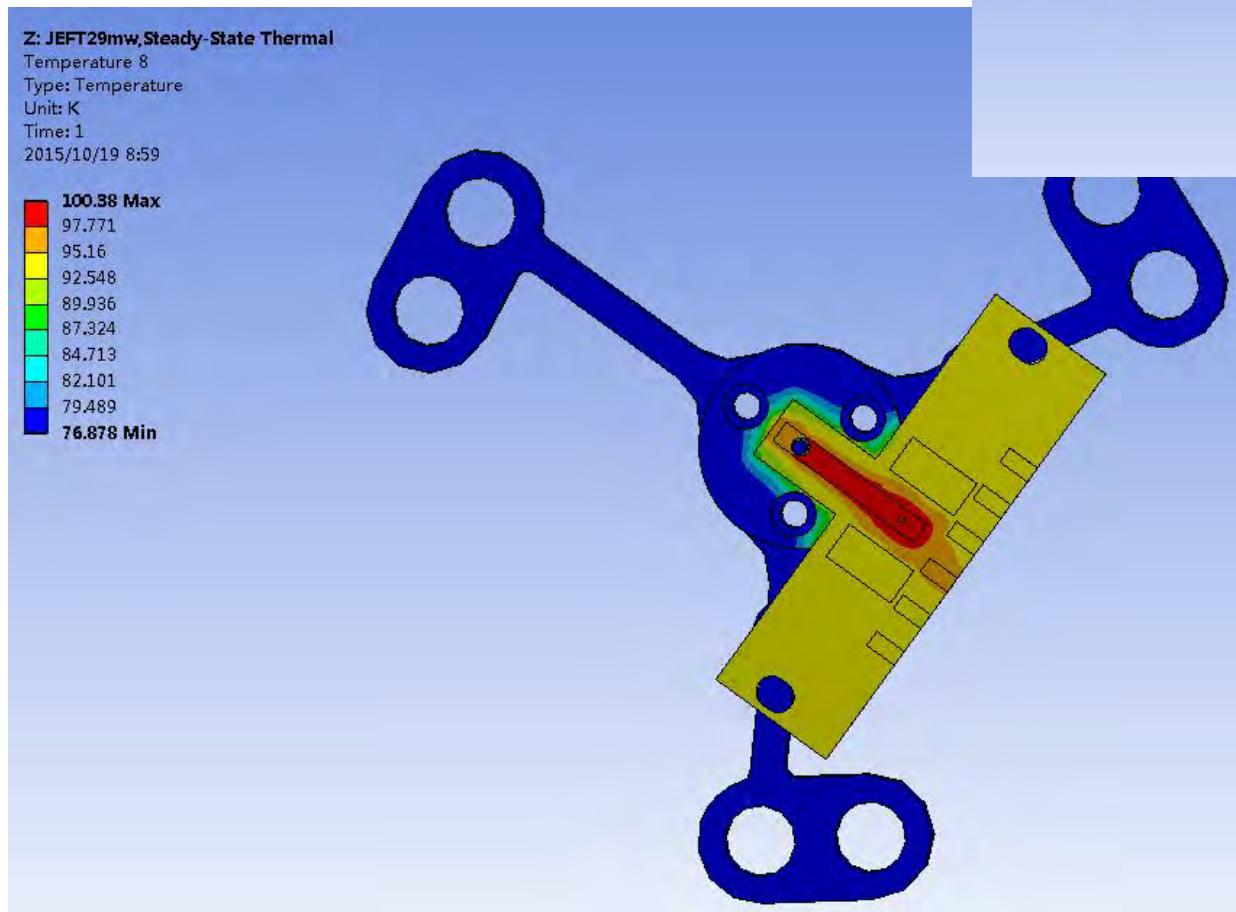


f 20

CDEX-10X design: Thermal Simulation Analysis (4)

Heat Source	Temperature distribution @ JFET	Temperature distribution @ PCB
5 mW	<p>X: JFET 5mw Steady-State Thermal Temperature 2 Type: Temperature Unit: K Time: 1 2015/10/15 10:39</p> <p>81.144 Max 81.139 81.134 81.129 81.124 81.118 81.113 81.108 81.103 81.098 Min</p> <p>~81K</p>	<p>X: JFET 5mw Steady-State Thermal Temperature 5 Type: Temperature Unit: K Time: 1 2015/10/15 10:41</p> <p>81.11 Max 80.872 80.695 80.397 80.16 79.922 79.685 79.447 79.21 78.972 Min</p> <p>79K-81K</p>
10 mW	<p>X: JFET10mw,Steady-State Thermal Temperature 3 Type: Temperature Unit: K Time: 1 2015/10/14 16:18</p> <p>85.323 Max 85.312 85.302 85.292 85.282 85.271 85.261 85.251 85.24 85.23 Min</p> <p>-85K</p>	<p>X: JFET10mw,Steady-State Thermal Temperature 7 Type: Temperature Unit: K Time: 1 2015/10/14 17:25</p> <p>85.253 Max 84.779 84.305 83.831 83.357 82.883 82.409 81.935 81.461 80.997 Min</p> <p>81K-85K</p>

CDEX-10X design: Thermal Simulation Analysis (5)



29mW is
needed for JFET
to be heated to
100k

Summary & Outlook

- Progress have been achieved in HPGe detector fabrication;
 - New surface treatment method
 - New electrode configuration and assembling method
- For CDEX-10X:
 - The design is finished;
 - All the sub-systems and components are under processing and debugging;
 - The assembling and test will begin from the coming December.
- **X=? Hopefully:**
 - X=2 × 0.5,
 - By the mid of 2016, functional test finished
 - By the end of 2016, performance test finished
 - X=1, by the end of 2017